

terminal area or the region assigned to the terminal area; and

D) in a second phase effecting a connection of the wire conductor to the terminal area with a connecting instrument and the wire conductor is connected while being fixed on the coil
10 substrate and extending in parallel to the surface plane of the windings of the wire coil.

Claim 53 has not been changed by this Amendment and continues to read as follows:

¹⁴
53. The process according to claim ¹40, wherein a rotationally symmetrical coil is formed with a wire conductor wired on a substrate taking the form of a winding support and rotating relative to a wiring device.

Please amend claim 79 as follows:

~~53~~
79. (Once Amended) A process for arranging a wire conductor on a substrate to form a wire coil connected to a chip unit, the process comprising the steps of:

D2) providing the substrate with a recess for receiving the chip unit;
inserting the chip unit into said recess;
5 guiding the wire conductor over said recess with said inserted chip and away from said recess with a wire guiding device;

[subsequently] subsequent to said step of guiding the wire conductor, fixing the wire conductor to the substrate by ultrasonically vibrating the wire guiding device and the wire conductor during said fixing, said guiding and said fixing including forming the wire coil from
10 the wire conductor;

[subsequently] subsequent to said step of fixing the wire conductor, connecting the wire conductor to a terminal area fixed to the substrate and of the chip unit with the wire conductor connected to the terminal area extending in parallel to the surface plane of the windings of the wire coil.

Claim 80 has not been changed by this Amendment and continues to read as follows:

³¹
80. The process in accordance with claim ³⁰~~79~~, wherein:

said inserting of the chip unit into said recess is performed after said guiding and said fixing.

Claim 81 has not been changed by this Amendment and continues to read as follows:

³²
~~81~~. The process in accordance with claim ³⁰~~79~~, wherein:

said recess extends through said substrate;

said fixing of the wire conductor is on one side of the substrate and said inserting of the chip unit is from another opposite side of the substrate.

Claim 82 has not been changed by this Amendment and continues to read as follows:

³³
~~82~~. The process in accordance with claim ³¹~~80~~, wherein:

said recess extends through said substrate;

said fixing of the wire conductor is on one side of the substrate and said inserting of the chip unit is from another opposite side of the substrate.